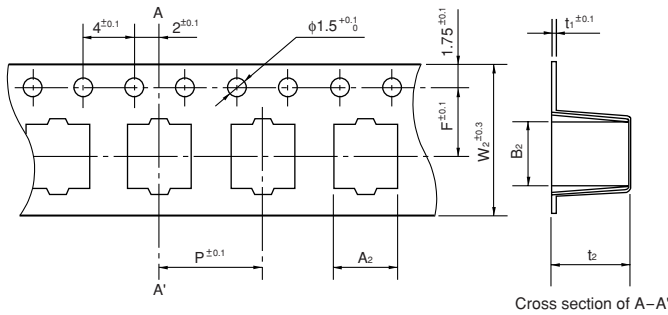
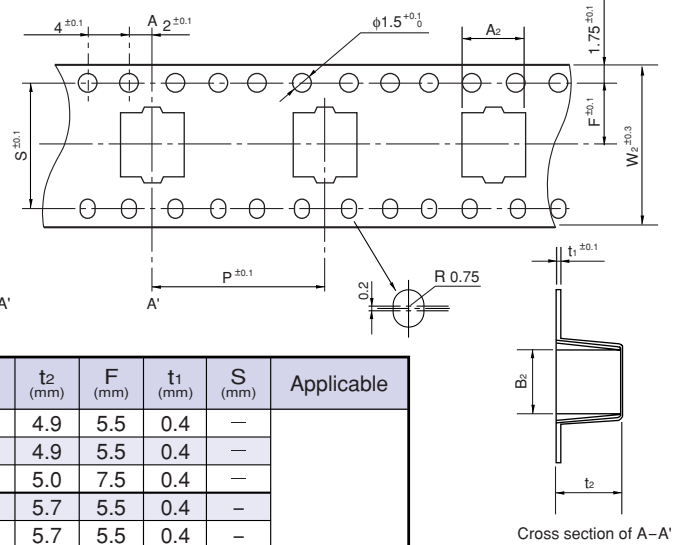
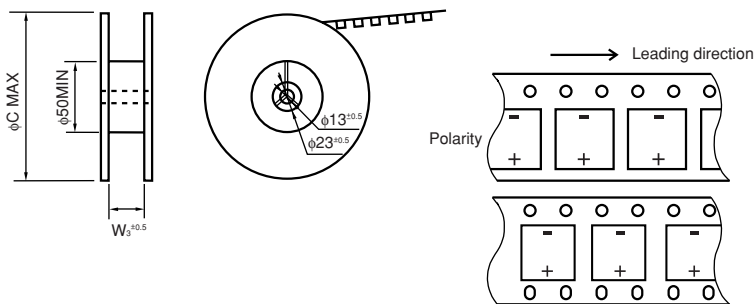


object : Chip type capacitors
◆ TAPING DIMENSIONS
Fig.1

Fig.2


Size	W ₂ (mm)	A ₂ (mm)	B ₂ (mm)	P (mm)	t ₂ (mm)	F (mm)	t ₁ (mm)	S (mm)	Applicable
φ4 × 4.5	12.0	4.7	4.7	8	4.9	5.5	0.4	—	Fig.1
φ5 × 4.5	12.0	5.7	5.7	12	4.9	5.5	0.4	—	
φ6.3 × 4.5	16.0	7.0	7.0	12	5.0	7.5	0.4	—	
φ3 × 5.5	12.0	3.6	3.6	8	5.7	5.5	0.4	—	
φ4 × 5.5	12.0	4.7	4.7	8	5.7	5.5	0.4	—	
φ5 × 5.5	12.0	5.7	5.7	12	5.7	5.5	0.4	—	
φ6.3 × 5.5	16.0	7.0	7.0	12	5.7	7.5	0.4	—	
φ4 × 6.1	12.0	4.7	4.7	8	6.2	5.5	0.4	—	
φ5 × 6.1	12.0	5.7	5.7	12	6.2	5.5	0.4	—	
φ6.3 × 6.1	16.0	7.0	7.0	12	6.2	7.5	0.4	—	
φ6.3 × 8	16.0	7.0	7.0	12	8.2	7.5	0.4	—	
φ8 × 6.5	16.0	8.7	8.7	12	6.8	7.5	0.4	—	
φ8 × 10.5	24.0	8.7	8.7	16	11.0	11.5	0.4	—	
φ10 × 10.5	24.0	10.7	10.7	16	11.0	11.5	0.4	—	
φ4 × 7	16.0	4.7	4.7	8	7.4	7.5	0.5	—	
φ5 × 7	16.0	5.7	5.7	12	7.2	7.5	0.5	—	
φ6.3 × 7	16.0	7.0	7.0	12	7.3	7.5	0.4	—	
φ12.5 × 13.5	32.0	14.0	14.0	24	14.0	14.2	0.5	28.4	Fig.2
φ12.5 × 16	32.0	14.0	14.0	24	16.3	14.2	0.5	28.4	
φ16 × 16.5	44.0	17.5	17.5	28	16.8	20.2	0.5	40.4	
φ16 × 21.5	44.0	17.5	17.5	28	21.8	20.2	0.5	40.4	
φ18 × 16.5	44.0	19.5	19.5	32	16.8	20.2	0.5	40.4	
φ18 × 21.5	44.0	19.5	19.5	32	21.8	20.2	0.5	40.4	
φ18 × 21.5	44.0	19.5	19.5	32	21.8	20.2	0.5	40.4	

◆ TAPING REEL AND PACKING QUANTITY


Size	W ₃ (mm)	φC (mm)	Quantity/reel	Standard Shipping Carton Quantity
φ3 × 5.5	14	382	2,000	10,000
φ4 × 4.5, 5.5, 6.1	14	382	2,000	10,000
φ5 × 4.5, 5.5, 6.1	14	382	1,000	5,000
φ6.3 × 4.5, 5.5, 6.1	18	382	1,000	5,000
φ6.3 × 8	18	382	900	4,500
φ4 × 7	18	382	1,500	7,500
φ5 × 7	18	382	1,000	5,000
φ6.3 × 7	18	382	1,000	5,000
φ8 × 6.5	18	382	1,000	5,000
φ8 × 10.5	26	382	500	2,000
φ10 × 10.5	26	382	500	2,000
φ12.5 × 13.5	34	332	200	600
φ12.5 × 16	34	332	150	450
φ16 × 16.5, φ18 × 16.5	46	332	125	250
φ16 × 21.5, φ18 × 21.5	46	332	75	150

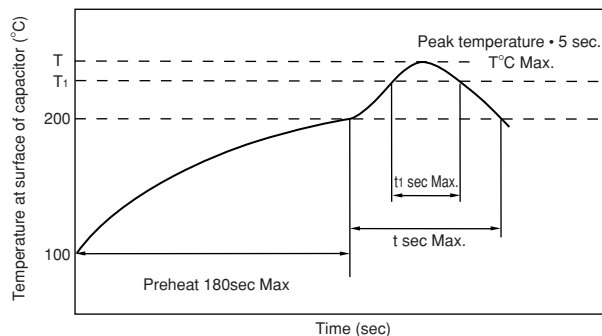
Reusable reels are available according to your request.
Please consult in regard to establishing supply and withdrawal system.

◆ LEAD FREE TYPE REFLOW SOLDERING CONDITION

• Size $\phi 3 \sim \phi 10$

- 1) Temperature at surface of capacitor shall not exceed $T^{\circ}\text{C}$.
- 2) Period that temperature at surface of capacitor becomes more than 200°C and $T_1^{\circ}\text{C}$ shall not exceed t and t_1 seconds, respectively.
- 3) Preheat shall be made at $100^{\circ}\text{C} \sim 200^{\circ}\text{C}$ and for maximum 180 seconds.

Series	Size	$T(^{\circ}\text{C})$	$T_1(^{\circ}\text{C})$	$t(\text{sec})$	$t_1(\text{sec})$	Reflow cycle
SEV NSEV SKV NSKV SGV SZV TZV SXV SSV	$\phi 3 \sim \phi 6.3$	250	230	90	40	1
	$\phi 8$	240	230	90	30	1
	$\phi 10$	235	230	60	30	1
SJV SLV	$\phi 4 \sim \phi 6.3$	240	220	60	40	1
JEV JKV	$\phi 4 \sim \phi 6.3$	260	217	-	60	2
JGV JZV	$\phi 8, \phi 10$	250	217	-	60	2



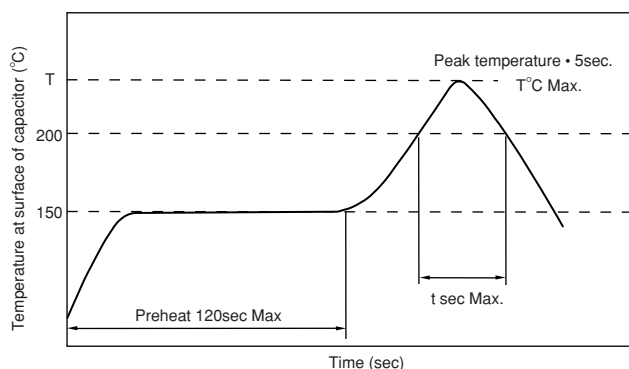
Please contact us if the condition is over the maximum.

• Size $\phi 12.5 \sim \phi 18\text{mm}$

- 1) Temperature at surface of capacitor shall not exceed $T^{\circ}\text{C}$.
- 2) Period that temperature at surface of capacitor becomes more than 200°C shall not exceed t seconds.
- 3) Preheat shall be made at maximum 150°C and for maximum 120 seconds.
- 4) Reflow soldering process shall be 1 cycle.

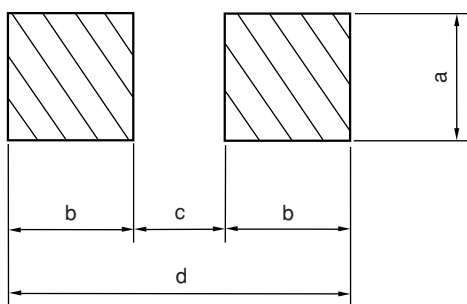
Series	Size	$T(^{\circ}\text{C})$	$t(\text{sec})$
SEV SGV	$\phi 12.5 \sim \phi 18$	215	20

*Temperature at terminal of capacitor ($\phi 8 \sim \phi 18$) shall not exceed 230°C .



*Please contact us if the condition is over the maximum.

◆ RECOMMENDED LAND SIZE



Size	a	b	c	d
$\phi 3$	1.6	2.2	0.8	5.2
$\phi 4$	1.6	2.6	1.0	6.2
$\phi 5$	1.6	3.0	1.4	7.4
$\phi 6.3$	1.6	3.5	2.1	9.1
$\phi 8 \times 6.5$	1.6	4.5	2.1	11.1
$\phi 8 \times 10.5$	2.2	4.1	3.0	11.2
$\phi 10 \times 10.5$	2.2	4.3	4.5	13.1
$\phi 12.5$	2.5	6.0	5.0	17
$\phi 16$	3	6.5	8.0	21
$\phi 18$	3	7.5	8.0	23